

L37-3F 導熱矽膠 Thermal Pad



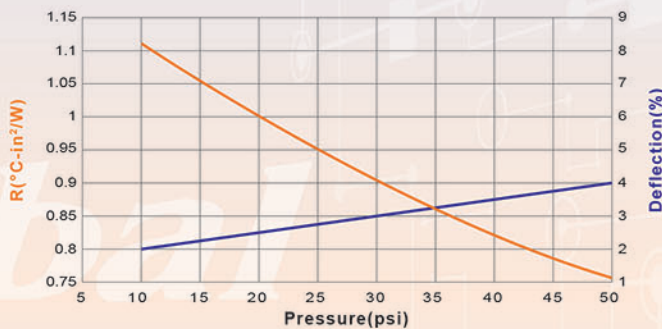
產品特性 Features

Made from silicone, thermal conductive particles, fiberglass
由矽膠、導熱聚合物及玻璃纖維組成
Low elongation 低延展率、不易變形
Electrical insulation 高絕緣性
Easy to assemble 操作性佳

產品應用端 Applications

High voltage application 適合高壓輸出之電子裝置及散熱片間
Electronic components: IC, CPU, MOS, LED, Mother Board,
Power Supply, Heat Sink, LCD-TV, Notebook, PC,
Telecom Device, Wireless Hub etc.

熱阻抗VS.壓力VS.變形量示意圖 Thermal Resistance VS. Pressure VS. Deflection

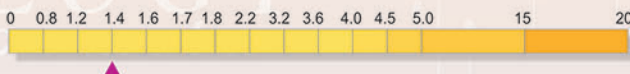


Pressure (psi)	R (°C-in²/W)	Deflection (%)
10	1.11	2
30	0.91	3
50	0.76	4

產品物性 Properties

REACH Compliant 符合REACH規範 RoHS Compliant 符合RoHS規範 UL Compliant 符合UL規範

Thermal Conductivity 導熱係數: 1.4 W/mK



Hardness 軟硬度: 90 (Shore A)



Testing sample thickness: 0.3mm

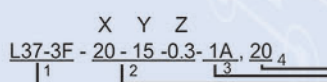
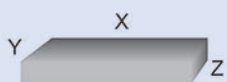
In "Thermal resistance V.S. Pressure V.S. Deflection" chart, L37-3F provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower, and deflection percentage gets higher. L37-3F provides good compliance and softness.

Properties	L37-3F	Unit	Tolerance	Test Method
Thermal Conductivity 導熱係數	1.4	W / mK	±0.14	ASTM D5470
Thickness 厚度 (the thickness can be ordered)	0.25/0.3/0.45	mm	-	ASTM D374
	0.0098/0.0118/0.0177	inch	-	ASTM D374
Color 顏色	Yellow黃	-	-	Visual目視
Flame Rating 耐燃等級	V-0	-	-	UL 94
Dielectric Breakdown Voltage 耐電壓	3/4/5	KV	±0.3/±0.4/±0.5	ASTM D149
Weight Loss 重量損失	<1	%	-	ASTM E595
Density 密度	2	g / cm ³	±0.2	ASTM D792
Working Temperature 工作溫度	-40~+200	°C	-	-
Volume Resistance 體積阻抗	>10 ¹¹	Ohm-m	-	ASTM D257
Elongation 延展率	5	%	-	ASTM D412
Tensile Strength 抗拉強度	150	Kgf / cm ²	-	ASTM D412
Standard Shape 標準形狀	Sheet ones 單片狀	-	-	-
Hardness 硬度	90	Shore A	±3	ASTM D2240

Need samples? 樣品需求?

Available to apply adhesive 可依需求背膠

Pre-cut for different shapes 可依需求沖型裁切
Roll type is available 可製成捲材



1. Choose the P/N
2. Fill into size: X, Y, Z
3. Apply the adhesive or not? 0=none, 1A= one side, 2A= two sides
4. Fill the quantity you need